Meet our materials experts at PCIM Europe.

Between the 20th and 22nd of May, 2015 everything revolves around power electronics at the PCIM. Our molybdenum, tungsten, molybdenum copper and tungsten-copper (WCu) components for reliable heat dissipation in semiconductors will be there too.

Good thermal and electrical conductivity coupled with appropriate thermal expansion:

This makes molybdenum and tungsten ideally suited for cooling semiconductor-based components such as IGBT modules, RF packages, LED chips, semiconductor diodes, transistors and thyristors.

We manufacture both - semifinished products and customized heat spreaders, heat sinks and base plates from tungsten, molybdenum, molybdenum-copper (MoCu) and tungsten-
copper (WCu). We have adjusted the composition of these composite materials to perfectly meet the requirements of our customers.

Meet us:
PCIM Europe in Nürnberg/Germany
20. - 22. May 2014
Booth. No. 428 / Hall 6

Or find you local contact person here.